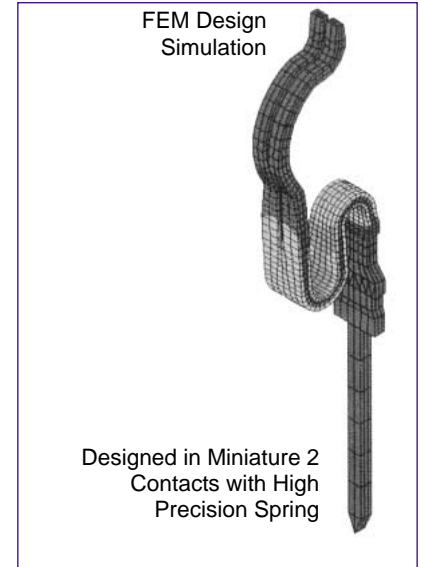
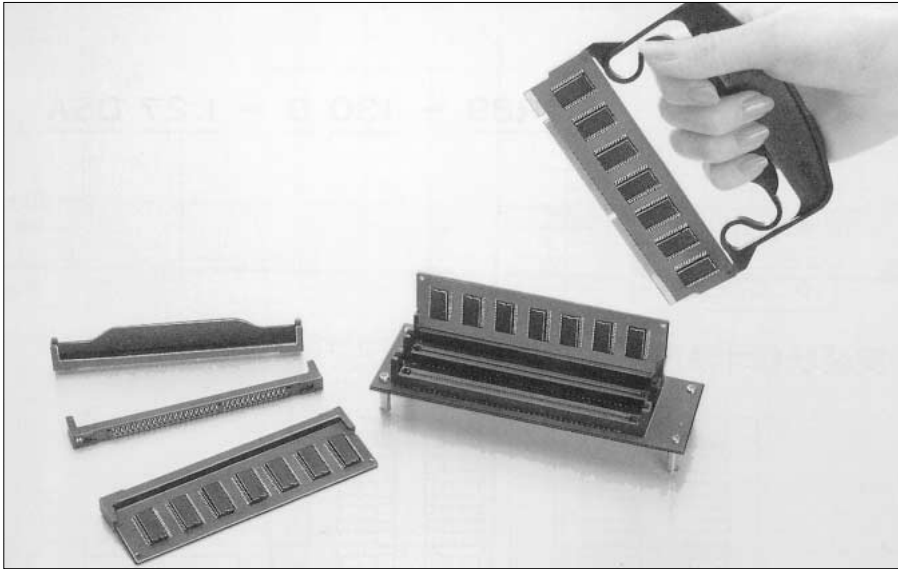


Socket for Memory Module Board

MCR89 Series



■ Features

1. High Reliability

This socket achieves high reliability in the horizontal contact spring system.

2. Low Insertion Force

This socket prevents mis-insertion force in the preload structure.

3. Easy Pattern Design

The dip contact through-hole diameter is only $\phi 0.5$, and simplifies the pattern design.

4. Miniature Type and High Density Mounting

The low profile with 6.2mm height from the board is suitable for miniaturization of equipment. The 1.27mm pitch between contacts assures mounting with high density.

5. Wide Effective Mounting Area

This socket is capable of widening the effective mounting area on the module printed board, and secures retention function by easy locking.

6. Easy Board Mounting

The fixing pins are arranged in the same alignment as the contact, so as to easily install the connector in the board.

7. Accessories

Dust covers and jigs to remove the board are available.

■ Product Specifications

Rating	Current rating: 0.5A	Operating Temperature Range: -30 to +85°C (Note 1)	Storage Temperature Range: -10 to +60°C (Note 2)
	Voltage rating: 125V AC	Operating Humidity Range: 40 to 80%	Storage Temperature Range: 40 to 70% (Note 2)

Item	Specification	Conditions
1. Contact Resistance	1000M ohms min.	500A DC
2. Withstanding voltage	No flashover or insulation breakdown.	500V DC / 1 minute
3. Insulation Resistance	20m ohms max.	100mA
4. Vibration	No electrical discontinuity of 10 μ s or more	Frequency: 10 to 55 Hz, single amplitude of 0.75 mm, 2 hours in each of the 3 directions.
5. Humidity (Steady state)	Insulation Resistance: 1000M ohms min.	96 hours at temperature of 40°C and humidity of 90% to 95%
6. Temperature Cycle	No damage, cracks, or parts looseness.	5 cycles under following condition; Temperature : -55: 30 minutes \rightarrow +5 to 35°C: 5 minutes max. \rightarrow 85°C : 30 minutes \rightarrow 15- to 30°C 5 minutes max.)
7. Durability (Insertion/withdrawal)	Contact resistance: 20m ohms max.	200 cycles
8. Resistance to Soldering heat	No deformation of components affecting performance.	Manual soldering: 300°C for 3 seconds

Note 1: Includes temperature rise caused by current flow.

Note 2: The term "storage" refers to products stored for long period of time prior to mounting and use. Operating Temperature Range and Humidity range covers non- conducting condition of installed connectors in storage, shipment or during transportation.

Material

Part	Material	Finish		Remarks
Insulator	PPS	Color : Brown		UL94V-0
Contact	Beryllium copper	Contact area	Selective gold plating	—
		Lead area	Solder plating	
Lock pin	Copper alloy	Solder plating		—

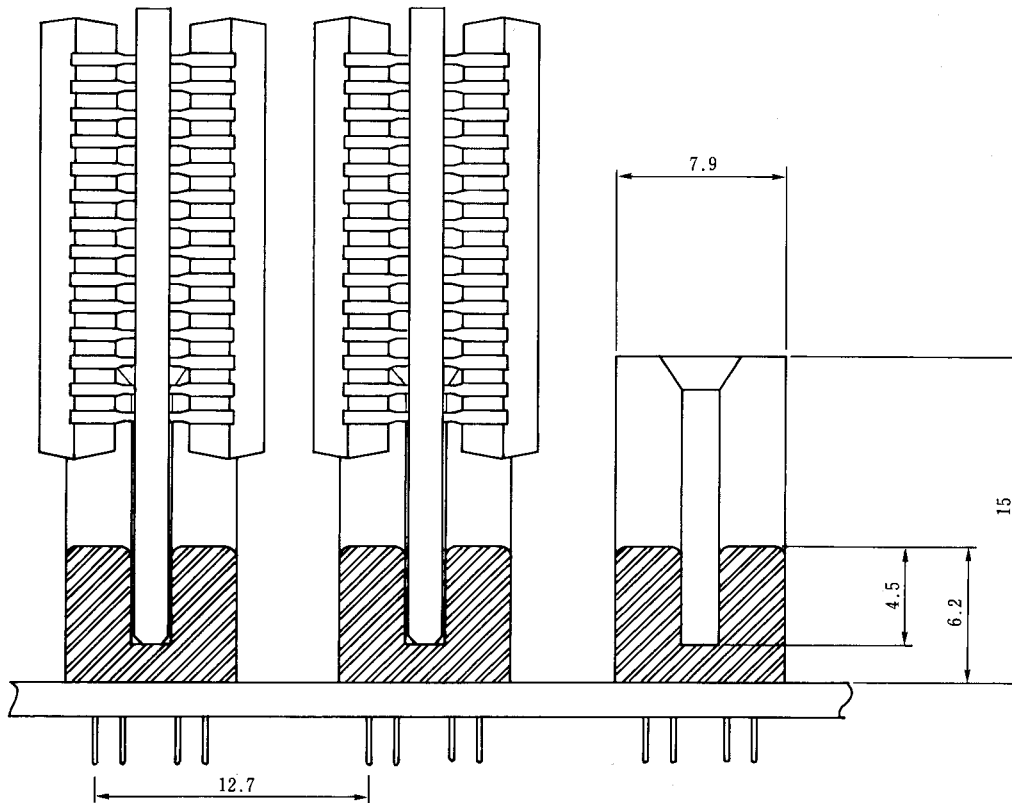
Ordering Information

MCR89 - 130 D - 1.27 DSA

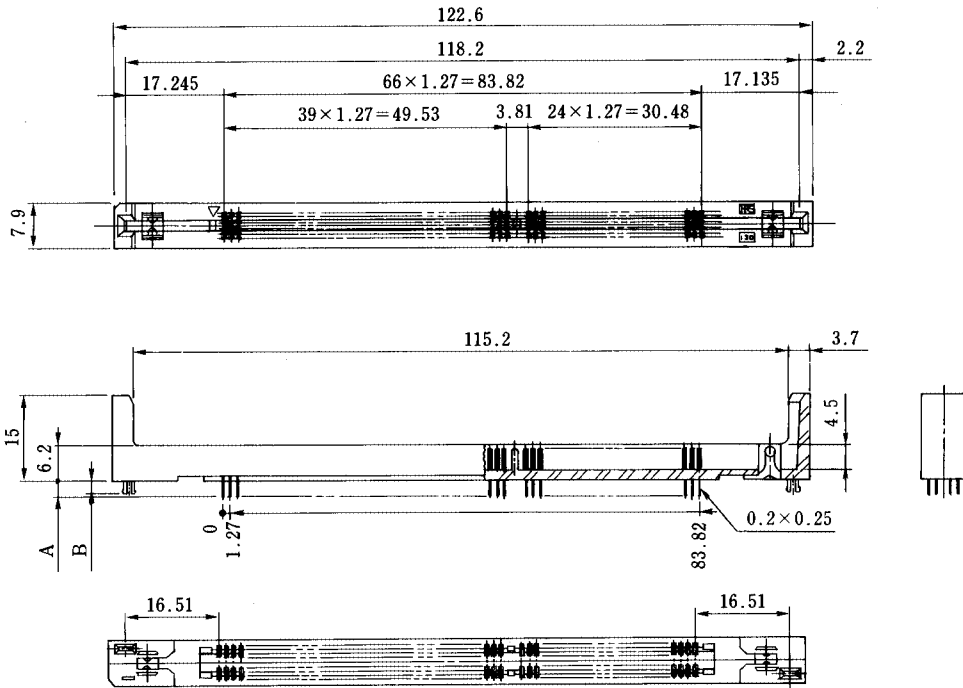
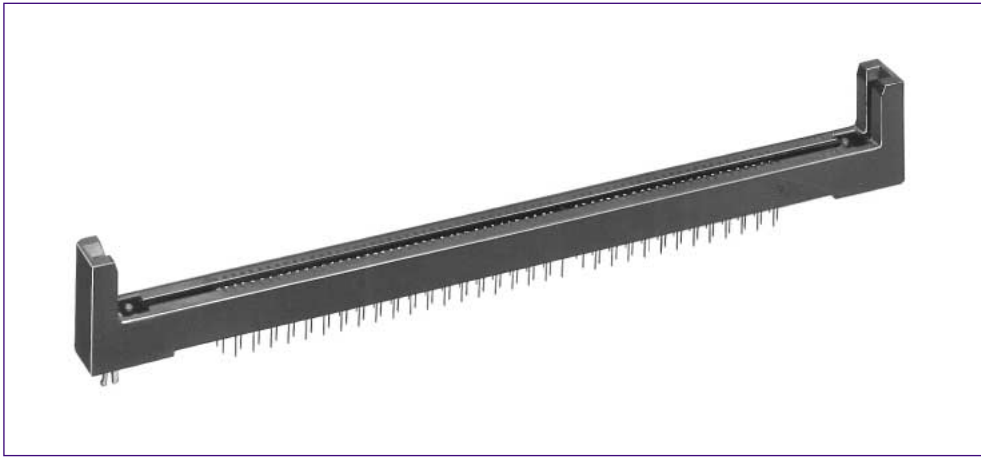
① ② ③ ④ ⑤

① Series Name: MCR89	⑤ Board installation type DSA: Straight dip type, board thickness 1.6mm DSC: Straight dip type, board thickness 2.6mm
② Number of Contacts: 130	
③ D: Double row	
④ Contacts Pitch: 1.27mm	

Mounting Dimensions



■ Dip Straight Type

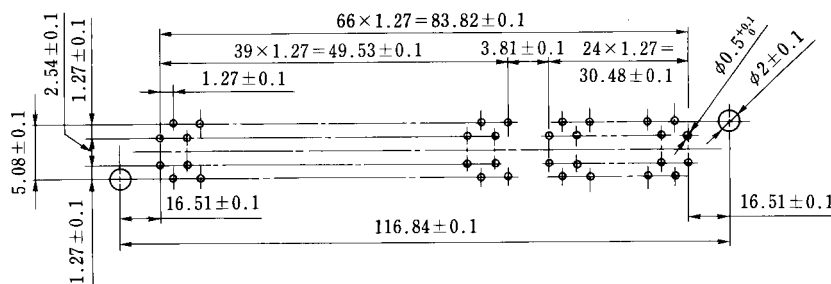


Unit: mm

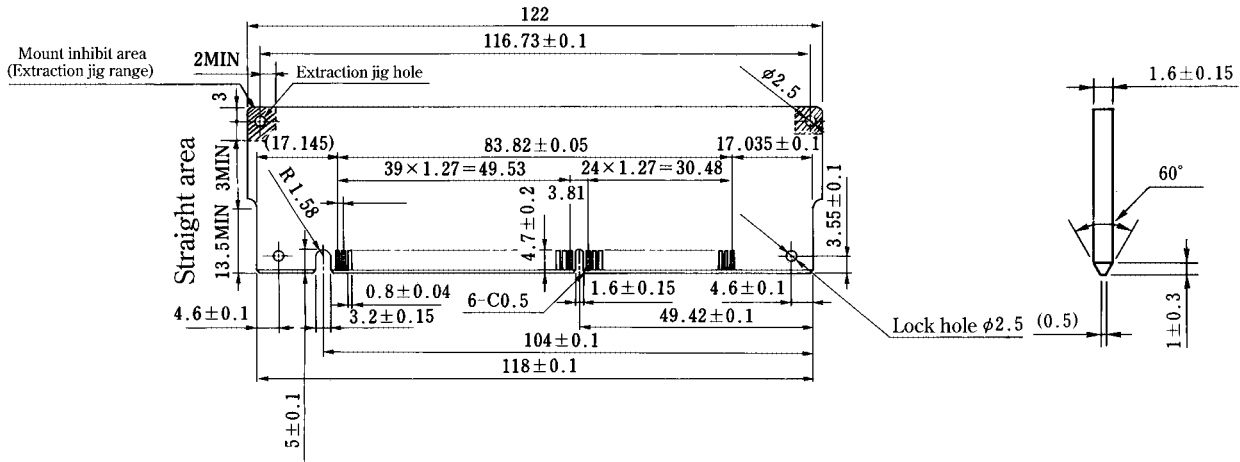
Part Number	CL No.	Number of Contacts	A	B
MCR89-130D-1.27DSA(01)	548-0173-0-01	130	2.8	2.3
MCR89-130D-1.27DSC(01)	548-0185-9-01		3.8	3.4

Note: 25 pieces are packaged in one set for sale. The above table indicates a packaging of 25 pieces.

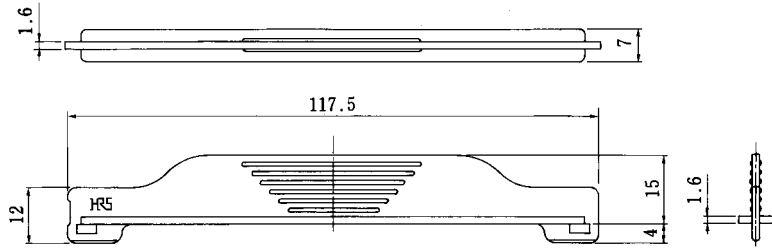
◆ PCB mounting pattern



◆ Recommended Module Board Dimensions



■ Dust Cover



Part Number	CL No.	Material	Finish
MCR89-130D-DC(01)	548-0180-5-01	ABS	Black

Note: 100 pieces are packaged in one set for sale. The above table indicates a packaging of 100 pieces.

■ Module Board Extraction Jig



Operating Instruction



(1) Insert the jig protrusion in the board hole. Grasping the handle, pull the board up.

(2) By loosening force, the board is removed from the jig.

Part Number	CL No.	Material	Finish
MCR89-130D-EJ	548-0183-3	Polyamid resin	Black